L Number	Hits	Search Text	DB	Time stamp
1	237	(optical and receiver and module).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:45
2	4	((optical and receiver and module).ti.) and (silicon adj1 wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:49
4	485	(optical with receiv$3) and (crystal adj1 orientation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:50
5	283	((optical with receiv$3) and (crystal adj1 orientation)) and (silicon and (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:52
6	188	(((optical with receiv$3) and (crystal adj1 orientation)) and (silicon and (wafer or substrate))) and (hole or opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:52
7	84	((((optical with receiv$3) and (crystal adj1 orientation)) and (silicon and (wafer or substrate))) and (hole or opening)) and (optic$2 near2 (fiber$1 or fibre$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:53
8	24	(((((optical with receiv$3) and (crystal adj1 orientation)) and (silicon and (wafer or substrate))) and (hole or opening)) and (optic$2 near2 (fiber$1 or fibre$1))) and "112"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:05
9	3	1826272.pn. OR 5247597.pn. OR 548396981.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:58
10	11	6195495.pn. or 5778123.pn. or 5940562.pn. or 5343544.pn. or 5311604.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:06
11	3	(6195495.pn. or 5778123.pn. or 5940562.pn. or 5343544.pn. or 5311604.pn.) and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:07
12	1	((6195495.pn. or 5778123.pn. or 5940562.pn. or 5343544.pn. or 5311604.pn.) and silicon) and "112"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:22
13	48802	385/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:22
14	5361	385/$.ccls. and ((wafer or substrate) same fiber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:23

15	393	385/$.ccls. and ((wafer or substrate) with (hole or opening) same fiber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:35
16	358	(385/$.ccls. and ((wafer or substrate) with (hole or opening) same fiber)) and (module or device or receiv$3 or diode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:49
17	1	((385/$.ccls. and ((wafer or substrate) with (hole or opening) same fiber)) and (module or device or receiv$3 or diode)) and registration adj1 surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:33
18	0	((385/$.ccls. and ((wafer or substrate) with (hole or opening) same fiber)) and (module or device or receiv$3 or diode)) and key adj1 surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:34
19	5	((385/$.ccls. and ((wafer or substrate) with (hole or opening) same fiber)) and (module or device or receiv$3 or diode)) and alignment adj1 surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:34
20	4	385/$.ccls. and ((wafer or substrate) with (hole or opening) with (diamond or square or rectangle) same fiber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:35
22	49	((385/$.ccls. and ((wafer or substrate) with (hole or opening) same fiber)) and (module or device or receiv$3 or diode)) and (passive near5 alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 11:32
23	2	"20020025122"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 11:32